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AMENDMENT UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE
GROUP 1733
PATENT APPLICATION

AF 77W

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q62228

Yoshihisa FURUTA, et al.

Appln. No.: 09/719,422

Group Art Unit: 1733

Confirmation No.: 7788

Examiner: Barbara J. Musser

Filed: December 12, 2000

For: METHOD OF RESIN ENCAPSULATING SEMICONDUCTOR CHIP AND
PRESSURE-SENSITIVE ADHESIVE TAPE FOR ADHESION TO LEADFRAME AND
THE LIKE

AMENDMENT UNDER 37 C.F.R. § 1.116

MAIL STOP AF

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated May 25, 2005, please amend the above-identified application as follows on the accompanying pages.

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